

<b>PCN Number:</b>	20240529005.1	<b>PCN Date:</b>	May 31, 2024
<b>Title:</b>	Qualification of RFAB using qualified Process Technology, Die Change, and additional Assembly site & BOM options		
<b>Customer Contact:</b>	Change Management team	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	August 29, 2024	<b>Sample requests accepted until:</b>	June 30, 2024*
<b>*Sample requests received after June 30, 2024 will not be supported.</b>			
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input checked="" type="checkbox"/>	Wafer Fab Process

## PCN Details

### Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology and additional Assembly site & BOM options for the device listed below.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
SH-BIP1	HCMOS	150 mm	RFAB	LBC9	300 mm

The die was also changed as a result of the process change.

### Group 1 BOM Table (FAB/Process migration, die change plus BOM update):

	Current	New
Bond Wire composition/diameter	Cu, 0.96 or 1.0 mil	<b>Cu, 0.8 mil</b>

### Group 2 BOM Table (RFAB/Process migration, die change plus MLA as new Assembly site & BOM update):

	FMX	FMX new	MLA
Bond Wire composition/diameter	Cu, 0.96	Cu, 0.8 mil	<b>Cu, 0.8 mil</b>

### Group 3 BOM Table (RFAB/Process migration, die change plus CDAT as new Assembly site & BOM update (RGY)):

	MLA	CDAT
Mount Compound	4205846	<b>4207123</b>
Mold Compound	4208625	<b>4222198</b>
Bond Wire composition/diameter	Cu, 0.96 mil	<b>Cu, 0.8 mil</b>

### Group 4 BOM Table (RFAB/Process migration, die change plus CDAT as new Assembly site & BOM update (DCK/DBV)):

	HFTF	HNA	ASEWH	CDAT
Lead Finish	Matte Sn	NiPdAu	NiPdAu	<b>Matte Sn</b>
Mount Compound	SID# A-03	SID#400180	SID#1120999A2	<b>4207123</b>
Mold Compound	SID#R-27	SID#450179	SID#3010999A7	<b>4222198</b>

Bond Wire composition/diameter	Cu, 1.0 mil	Au, 0.6 mil	Au or Cu, 0.8 mil or 1.0 mil	<b>Cu, 0.8 mil</b>
Device Marking (DBV device)	NEBJ	NEBS	NEB3	<b>3JRH</b>
Device Marking (DCK device)	WAJ	WAS	WA3	<b>1TR</b>

**Group 5 BOM Table (RFAB/Process migration, die change plus FMX as new Assembly site & BOM update):**

	MLA	MLA new	<b>FMX</b>
Bond Wire composition/diameter	Cu, 0.96 mil	Cu, 0.8 mil	<b>Cu, 0.8 mil</b>

Qual details are provided in the Qual Data Section.

**Reason for Change:**

These changes are part of our multiyear plan to transition products from our 150-milimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Impact on Environmental Ratings:**

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change

**Changes to product identification resulting from this PCN:****Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

**Die Rev:****Current****New**

Die Rev [2P]	Die Rev [2P]
A,B,H,J,K,M,-	<b>A</b>

**Assembly Site Information:**

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASEWH	AWH	CHN	Weihai
HNA	HNT	THA	Ayutthaya
MLA	MLA	MYS	KUALA LUMPUR
TI Mexico	MEX	MEX	Aguascalientes
HFTF	HFT	CHN	Hefei
<b>CDAT</b>	<b>CDA</b>	<b>CHN</b>	<b>Chengdu</b>

Sample product shipping label (not actual product label)

**Product Affected:****Group 1 Device List (FAB/Process migration, die change plus BOM update):**

CD74ACT157PWR	SN74AC14N	SN74ACT00PWR	SN74ACT14PWR
CD74ACT257M96	SN74AC14NSR	SN74ACT04DR	SN74ACT32PWR
SN74AC00DR	SN74AC14NSRG4	SN74ACT04PWR	SN74ACT74PWR
SN74AC00PWR	SN74AC14PWR	SN74ACT08DR	SN74ACT86PWR
SN74AC04NSR	SN74AC32DR	SN74ACT08PWR	SN74AHC139PWR
SN74AC04PWR	SN74AC32PWR	SN74ACT08PWRG4	SN74AHC174PWR
SN74AC08PWR	SN74AC74DR	SN74ACT10PWR	SN74AHC367PWR
SN74AC10PWR	SN74AC74PWR	SN74ACT11PWR	SN74AHCT174PWR
SN74AC11PWR	SN74AC86PWR	SN74ACT14DR	SN74AHCT367PWR
SN74AC14DR			

**Group 2 Device List (RFAB/Process migration, die change plus MLA as new Assembly site & BOM update):**

CD74AC257M96	SN74AHC157DR	SN74AHCT138DR	SN74AHCT594DR
CD74ACT157M96	SN74AHC595DR	SN74AHCT367DR	SN74AHCT595DR
SN74AHC138DR			

**Group 3 Device List (RFAB/Process migration, die change plus CDAT as new Assembly site & BOM update (RGY));**

SN74AHC139RGYR	SN74AHC157RGYR
----------------	----------------

**Group 4 Device List (RFAB/Process migration, die change plus CDAT as new Assembly site & BOM update (DCK/DBV));**

SN74LV1T00DCKR	SN74LV1T02DBVR
----------------	----------------

**Group 5 Device List (RFAB/Process migration, die change plus FMX as new Assembly site & BOM update):**

CD74AC00M96	CD74ACT00M96	CD74ACT74M96	SN74AC86DR
CD74AC04M96	CD74ACT04M96	SN74AC04DR	SN74ACT00DR
CD74AC08M96	CD74ACT08M96	SN74AC08DR	SN74ACT32DR
CD74AC14M96	CD74ACT14M96	SN74AC10DR	SN74ACT74DR
CD74AC32M96	CD74ACT32M96	SN74AC11DR	SN74ACT86DR
CD74AC74M96			

For alternate parts with similar or improved performance, please visit the product page on [TI.com](https://www.ti.com)

**R-CHG-2311-044**

TI Information  
Selective Disclosure

**Qualification Report**

**GATORADE BD15.5 - 14NS\_MLA Qual Driver SN74AC14NSR in MLA using 14-pin NS pkg**  
**Approve Date 15-MAY -2024**

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC14NSR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74LVC8T245NSR	QBS Reference: SN74LV244AQDGSRQ1	QBS Reference: PCMI1794AQDBRQ1
HAST	A2	Biased HAST	130C/85%RH	192 Hours	-	3/231/0	-	1/77/0	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	1/77/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/231/0	1/45/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	1/77/0	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	3/2400/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC14NSR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74LVC8T245NSR	QBS Reference: SN74LV244AQDGSRQ1	QBS Reference: PCM1794AQDBRQ1
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	1/10/0	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	-	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	1/30/0	3/90/0

- QBS: Qual By Similarity
- Qual Device SN74AC14NSR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-044

**R-CHG-2311-046**

## Qualification Report

**GATORADE BD15.5 - 14PW\_MLA QBS Qual SN74AC04PWR in MLA using 14-pin PW pkg**  
**Approve Date 15-MAY -2024**

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC04PWR	Qual Device: SN74AC14PWR	Qual Device: SN74ACT04PWR	Qual Device: SN74ACT14PWR	QBS Reference: SN74HCS74QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC04PWR	Qual Device: SN74AC14PWR	Qual Device: SN74ACT04PWR	Qual Device: SN74ACT14PWR	QBS Reference: SN74HCS74QPWRQ1
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0

- QBS: Qual By Similarity
- Qual Device SN74AC04PWR is qualified at MSL1 260C
- Qual Device SN74AC14PWR is qualified at MSL1 260C
- Qual Device SN74ACT04PWR is qualified at MSL1 260C
- Qual Device SN74ACT14PWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-046

**R-CHG-2311-039**

## Qualification Report

GATORADE BD15.5 - 14D\_MLA Qual Driver CD74AC04M96 in MLA using 14-pin D pkg  
Approve Date 15-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>CD74AC04M96</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>SN74HCS74QDRQ1</u>	QBS Reference: <u>SN74AC04PWR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <u>CD74AC04M96</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>SN74HCS74QDRQ1</u>	QBS Reference: <u>SN74AC04PWR</u>
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	-

- QBS: Qual By Similarity
- Qual Device CD74AC04M96 is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-039

**R-CHG-2311-043**

## Qualification Report

GATORADE BD15.5 - 14N\_FMX Qual Driver SN74AC14N in FMX using 14-pin N pkg  
Approve Date 14-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC14N	QBS Reference: TLC339IN	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74AC14N
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	3/66/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC14N	QBS Reference: TLC339IN	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74AC14N
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	-

- QBS: Qual By Similarity
- Qual Device SN74AC14N is qualified at NOT CLASSIFIED NOT CLASSIFIED

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-043

**R-CHG-2311-042**



## Qualification Report

GATORADE BD15.5 - 14N\_MLA Qual Driver SN74AC14N in MLA using 14-pin N pkg  
Approve Date 14-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC14N	QBS Reference: SN74HC595N	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: LM2594HVN- ADJ/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/228/0
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC14N	QBS Reference: SN74HC595N	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: LM2594HVN- ADJ/NOPB
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	3/66/0	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	-

- QBS: Qual By Similarity
- Qual Device SN74AC14N is qualified at NOT CLASSIFIED NOT CLASSIFIED

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-042

**R-CHG-2311-041**

## Qualification Report

**GATORADE BD15.5 - 14D\_FMX Qual Driver CD74AC04M96 in FMX using 14-pin D pkg**  
**Approve Date 15-MAY -2024**

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">CD74AC04M96</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">LM393BIDR</a>	QBS Reference: <a href="#">CD74AC04M96</a>	QBS Reference: <a href="#">SN74AC04PWR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">CD74AC04M96</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">LM393BIDR</a>	QBS Reference: <a href="#">CD74AC04M96</a>	QBS Reference: <a href="#">SN74AC04PWR</a>
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	2/6/0	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	2/6/0	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	2/6/0	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-	-
FTY	E6	Final Test Yield	-	-	-	-	1/1/0	-	-

- QBS: Qual By Similarity
- Qual Device CD74AC04M96 is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-041

**R-CHG-2403-113**

## Qualification Report

Gatorade BD10P5 PCN - 16 PW Comm ( 2Q23 ) in MLA  
Approve Date 10-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74AHCT367PWR</u>	Qual Device: <u>SN74AHCT174PWR</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>SN74LV8T594QPWRQ1</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74AHCT367PWR</u>	Qual Device: <u>SN74AHCT174PWR</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>SN74LV8T594QPWRQ1</u>
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	1/10/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0

- QBS: Qual By Similarity
- Qual Device SN74AHCT367PWR is qualified at MSL1 260C
- Qual Device SN74AHCT174PWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-113

**R-CHG-2403-115**

Qualification Report  
Gatorade BD10P5 PCN - 16 D Comm ( 2Q24 ) in MLA  
Approve Date 08-MAY-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN744HC158DB	Qual Device: SN744HC158DB	Qual Device: SN744HC158DB	Qual Device: SN744HC158DB	QBS Reference: SN744HC158DB	QBS Reference: SN744HC158DB	QBS Reference: SN744HC158DB	QBS Reference: SN744HC158DB	QBS Reference: SN744HC158DB	QBS Reference: SN744HC158DB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	1/77/0	-	-	-
UHAFT	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
UHAFT	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	1/77/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	1/77/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	3/135/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	-	145/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	1/77/0	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	345/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	345/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder	-	-	1/22/0	-	-	-	-	-	-	1/22/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	3/30/0	1/100	-	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	1/3/0	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0	1/3/0	1/3/0	-	-
LU	E4	Latch Up	Per JEDEC78	-	-	-	-	-	16/0	16/0	16/0	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per DataSheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	-	-	-	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/30/0	3/30/0	3/30/0	1/30/0	1/30/0	-

- QBS: Qual By Similarity
- Qual Device: SN744HC158DB is qualified at MSL1 260C
- Qual Device: SN744HC158DB is qualified at MSL1 260C
- Qual Device: SN744HC158DB is qualified at MSL1 260C
- Qual Device: SN744HC158DB is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JEDEC47 : 55C/125C/700 Cycles and 65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-115

**R-CHG-2403-116**

## Qualification Report

Gatorade BD10P5 PCN - 16D Comm ( 2Q24 ) FMX  
Approve Date 08-MAY -2024

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AHCT595DR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74LV8T594QPWRQ1	QBS Reference: SN74AHCT594DBR	QBS Reference: SN74AHCT138DR	QBS Reference: SN74AHCT367DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0	-	-	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-	-	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	1/77/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	1/45/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74AHCT595DR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74LV8T594QPWRQ1	QBS Reference: SN74AHCT594DBR	QBS Reference: SN74AHCT138DR	QBS Reference: SN74AHCT367DR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	-	-	1/22/0	-	1/22/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	1/10/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/6/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	3/90/0	-	-	-

- QBS: Qual By Similarity
- Qual Device SN74AHCT595DR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-116

**R-CHG-2403-117**

## Qualification Report

BD10p5 Redbull Q224- (RFAB) in CDAT using 16-pin RGY  
Approve Date 13-MAY -2024

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AHC157RGYR	Qual Device: SN74AHC157RGYR	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001	QES Reference: SN74AHC157RGYR001
HAST	A2	Biasd HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	1/77/0	1/77/0	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-	1/77/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	1/77/0	-	-	-	-	-
TC	A4	Temperature Cycle	-55C/150C	500 Cycles	-	-	3/231/0	3/231/0	1/77/0	1/77/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0	1/45/0	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	1/45/0	-	-	-	-
HTDL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	1/77/0	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2480/0	-	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	-	-	-	-	-	-
SD	C3	PB Solderability	8 Hours Steam Age	-	-	-	-	1/22/0	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	-	1/15/0	-	-	-	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	-	1/22/0	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/20/0	3/20/0	1/10/0	1/10/0	-	-	-	-
ESD	E2	ESD CDM	-	2000 Volts	-	-	-	1/3/0	-	-	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	1/3/0	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	7000 Volts	-	-	-	1/3/0	-	-	-	-	-	-
LU	E4	Leak-Up	Per JE5D78	-	-	-	1/6/0	1/6/0	1/6/0	1/6/0	1/3/0	1/3/0	-	-
CHAR	E5	Electrical Characterization	Per Delaheat Parameters	-	1/30/0	1/30/0	-	-	-	-	-	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	3/90/0	3/90/0	1/30/0	1/30/0	1/30/0	1/30/0

- Qual Device SN74AHC157RGYR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biasd HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTDL options based on an activation energy of 0.7 eV: 125C/8k Hours, 140C/480 Hours, 150C/200 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150C/8k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JE5D47: -55C/125C/700 Cycles and -55C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com>

TI Qualification ID: R-CHG-2403-117

R-CHG-2403-039

## Qualification Report

Commercial: AC00/AC08/AC32/AC86/ACT00/ACT08/ACT32/ACT86 (RFAB/LBC9) for April MLA TSSOP (MLA) - PCN  
GATORADE BD14  
Approve Date 13-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74ACT08PWR	QBS Reference: SN74HCS74QPWRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74ACT08PWR	QBS Reference: SN74HCS74QPWRQ1
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0

- QBS: Qual By Similarity
- Qual Device SN74ACT08PWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-039

**R-CHG-2402-042**

## Qualification Report

Commercial: AC00/AC08/AC32/AC86/ACT00/ACT08/ACT32/ACT86/AC257 (RFAB/LBC9) for April MLA SOIC (D) - PCN  
GATORADE BD14  
Approve Date 13-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74ACT08DR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74ACT08PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	3/231/0	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	3/45/0	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74ACT08DR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74ACT08PWR
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	-

- QBS: Qual By Similarity
- Qual Device SN74ACT08DR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-042

**R-CHG-2404-063**



## Qualification Report

Commercial: AC10/AC11/AC74/ACT74 / ACT157/ACT257/AC257 (RFAB/LBC9) for MAY MLA SOIC (D) - PCN GATORADE BD14  
Approve Date 16-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC10DR	Qual Device: SN74AC74DR	Qual Device: CD74AC257M96	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74AC10DR	QBS Reference: SN74AC74DR	QBS Reference: CD74AC257M96
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	3/135/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	3/45/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	3/45/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	3/30/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	-	1/3/0	1/3/0	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC10DR	Qual Device: SN74AC74DR	Qual Device: CD74AC257M96	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74HCS74QDRQ1	QBS Reference: SN74AC10DR	QBS Reference: SN74AC74DR	QBS Reference: CD74AC257M96
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/6/0	1/6/0	1/3/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	-	-	1/30/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0	3/90/0	-	-	-

- QBS: Qual By Similarity
- Qual Device SN74AC10DR is qualified at MSL1 260C
- Qual Device SN74AC74DR is qualified at MSL1 260C
- Qual Device CD74AC257M96 is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2404-063

**R-CHG-2402-082**

## Qualification Report

Commercial: AC10/AC11/AC74/ACT10/ACT11/ACT157/ACT74 (RFAB/LBC9) for May MLA TSSOP (PW) - PCN GATORADE BD14

Approve Date 14-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC74PWR	Qual Device: SN74AC10PWR	Qual Device: CD74ACT157PWR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74ACT08PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74AC74PWR	Qual Device: SN74AC10PWR	Qual Device: CD74ACT157PWR	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: SN74ACT08PWR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0	-

- QBS: Qual By Similarity
- Qual Device SN74AC74PWR is qualified at MSL1 260C
- Qual Device SN74AC10PWR is qualified at MSL1 260C
- Qual Device CD74ACT157PWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-082

**R-CHG-2312-023**

## Qualification Report

Commercial: AC10/AC11/AC257/AC74/ACT74/ACT157/ACT257/ (RFAB/LBC9) for May FMX SOIC (D) - PCN GATORADE BD14

Approve Date 16-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">SN74AC10DR</a>	Qual Device: <a href="#">SN74AC74DR</a>	Qual Device: <a href="#">CD74AC257M96</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">LM393BIDR</a>	QBS Reference: <a href="#">TL494IDR</a>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	3/231/0	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	3/231/0	-

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">SN74AC10DR</a>	Qual Device: <a href="#">SN74AC74DR</a>	Qual Device: <a href="#">CD74AC257M96</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">LM393BIDR</a>	QBS Reference: <a href="#">TL494IDR</a>
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	3/2400/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	-	-	3/228/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	-	2/6/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	1/3/0	-	2/6/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/3/0	1/6/0	2/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	-	3/90/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	-	-	1/1/0	-

**R-CHG-2402-043**

## Qualification Report

Commercial: AC00/AC08/AC32/AC86/ACT08/ACT00/ACT08/ ACT32/ACT86 (RFAB/LBC9) for April FMX SOIC (D) - PCN  
GATORADE BD14  
Approve Date 15-MAY -2024

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CD74ACT08M96	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: LM393BIDR	QBS Reference: TL494IDR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
UHASt	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0
UHASt	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/231/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	3/231/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	3/231/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	3/2400/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: CD74ACT08M96	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: LM393BIDR	QBS Reference: TL494IDR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	1/22/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-	2/6/0	-
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-	2/6/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/6/0	2/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	-
FTY	E6	Final Test Yield	-	-	-	-	1/1/0	-

- QBS: Qual By Similarity
- Qual Device CD74ACT08M96 is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2402-043

**R-CHG-2403-087**

Qualification Report  
BD13 DCK PCN CDAT  
Approve Date 03-MAY -2024

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LV1T00DCKR	QBS Reference: SN74LV1T34QDCKRQ1	QBS Reference: SN74HCS74QPWRO1	QBS Reference: TLV9061DBVR	QBS Reference: SN74LV1T125QDCKRQ1	QBS Reference: SN74AHCT1G125DCKR	QBS Reference: SN74AHCT1G00DCKR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	3/231/0	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	1/77/0	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	1/77/0	3/231/0	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	1/45/0	3/135/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	1/77/0	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/228/0	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: SN74LV1T00DCKR	QBS Reference: SN74LV1T34QDCKRQ1	QBS Reference: SN74HCS74QPWRO1	QBS Reference: TLV9061DBVR	QBS Reference: SN74LV1T125QDCKRQ1	QBS Reference: SN74AHCT1G125DCKR	QBS Reference: SN74AHCT1G00DCKR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	1/15/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	-	3/66/0	-	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk<1.67	-	-	1/10/0	3/30/0	-	1/10/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	1/3/0	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	1/3/0	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	-	1/6/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk<1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	-	1/30/0	-	-
FTY	E6	Final Test Yield	-	-	-	1/1/0	-	3/3/0	-	-	-

- QBS: Qual By Similarity
- Qual Device SN74LV1T00DCKR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-087

**R-CHG-2403-088**

**Qualification Report**  
**BD13 DBV PCN CDAT**  
**Approve Date 03-MAY -2024**

**Qualification Results**

**Data Displayed as: Number of lots / Total sample size / Total failed**

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74LV1T02DBVR</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>TLV9061IDBVR</u>	QBS Reference: <u>SN74LV1T125QDCKRQ1</u>	QBS Reference: <u>SN74AHCT1G125DBVR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	-	-
UHA	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: <u>SN74LV1T02DBVR</u>	QBS Reference: <u>SN74HCS74QPWRQ1</u>	QBS Reference: <u>TLV9061IDBVR</u>	QBS Reference: <u>SN74LV1T125QDCKRQ1</u>	QBS Reference: <u>SN74AHCT1G125DBVR</u>
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	3/228/0	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	3/228/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB- Free Solder;	-	-	-	3/66/0	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	1/10/0	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	1/3/0	-	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	1/3/0	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	-	1/6/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0

Type	#	Test Name	Condition	Duration	Qual Device: <a href="#">SN74LV1T02DBVR</a>	QBS Reference: <a href="#">SN74HCS74QPWRQ1</a>	QBS Reference: <a href="#">TLV9061IDBVR</a>	QBS Reference: <a href="#">SN74LV1T125QDCKRQ1</a>	QBS Reference: <a href="#">SN74AHCT1G125DBVR</a>
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	-	1/30/0	-
FTY	E6	Final Test Yield	-	-	-	-	3/3/0	-	-

- QBS: Qual By Similarity
- Qual Device SN74LV1T02DBVR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-088

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale ([www.ti.com/legal/termsofsale.html](http://www.ti.com/legal/termsofsale.html)) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.